150KHz, 2A PWM Buck DC/DC Converter

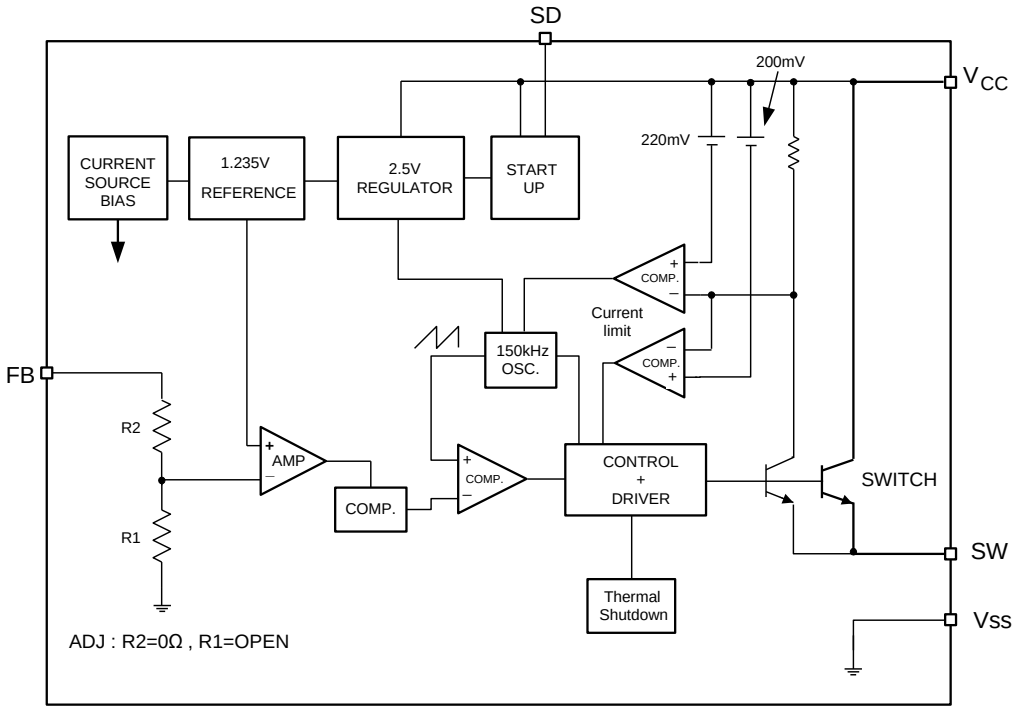
❖ GENERAL DESCRIPTION

The AX3008 series are monolithic IC designed for a step-down DC/DC converter, and own the ability of driving a 2A load without additional transistor. It saves board space. The external shutdown function can be controlled by logic level and then come into standby mode. The internal compensation makes feedback control having good line and load regulation without external design. Regarding protected function, thermal shutdown is to prevent over temperature operating from damage, and current limit is against over current operating of the output switch. If current limit function occurs and V_{FB} is down below 0.5V, the switching frequency will be reduced. The AX3008 series operates at a switching frequency of 150KHz thus allow smaller sized filter components than what would be needed with lower frequency switching regulators. The output version included fixed 3.3V, 5V, 12V, and an adjustable type. The chips are available in a standard SOP-8L package.

❖ FEATURES

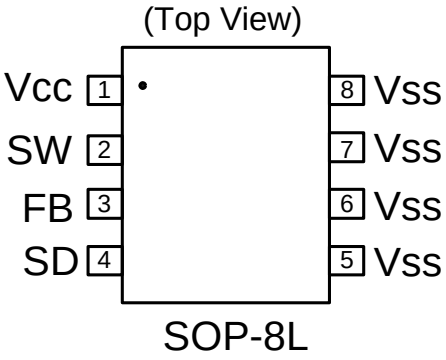
- Output voltage: 3.3V, 5V, 12V and adjustable output version.
- Adjustable version output voltage range, 1.23V to 20V.
- 150KHz fixed switching frequency.
- Voltage mode non-synchronous PWM control.
- Thermal-shutdown and current-limit protection.
- ON/OFF shutdown control input.
- Short Circuit Protect (SCP).
- Operating voltage can be up to 30V.
- Output load current: 2A.
- SOP-8L Pb-Free package.
- Low power standby mode.
- Built-in switching transistor on chip.

❖ BLOCK DIAGRAM



❖ PIN ASSIGNMENT

The package of AX3008 is SOP-8L. The pin assignment is given by:



Name	Description
V_{CC}	Operating voltage input
SW	Switching output
FB	Output voltage feedback control
SD	Power-off pin L：normal operation(Step-down) H：Step-down operation stopped (All circuits deactivated)
V_{SS}	GND pin

❖ ORDER/MARKING INFORMATION

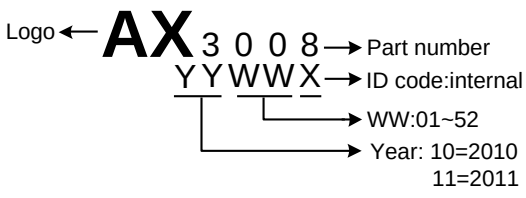
Order Information

AX3008- XX X X

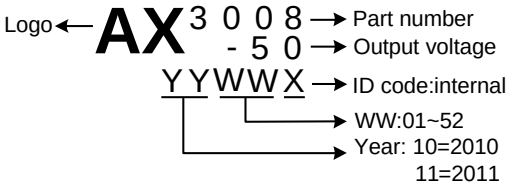
Output Voltage	Package Type	Packing
33:3.3V 50:5.0V 12: 12V Blank:ADJ	S: SOP-8L	Blank : Tube A : Taping

Top Marking

ADJ



FIX



❖ ABSOLUTE MAXIMUM RATINGS

Characteristics	Symbol	Rating	Unit
Maximum Supply Voltage	V_{CC}	+32	V
SD Pin Input Voltage	V_{SD}	-0.3 to V_{CC}	V
Feedback Pin Voltage	V_{FB}	-0.3 to 20	V
Output Voltage to Ground	V_{OUT}	-0.8	V
Power Dissipation Internally limited	PD	$(T_J-T_A) / \theta_{JA}$	W
Storage Temperature Range	T_{ST}	-65 to +150	°C
Operating Junction Temperature Range	T_J	-20 to +125	°C
Operating Supply Voltage	V_{OP}	+4.5 to +30	V
Output Current	I_{OUT}	2	A
Thermal Resistance from Junction to case	θ_{JC}	20	°C/W
Thermal Resistance from Junction to ambient	θ_{JA}	60	°C/W

Note: θ_{JA} is measured with the PCB copper area(need connect to V_{SS} pins) of approximately 1.5 in^2 (Multi-layer).

❖ ELECTRICAL CHARACTERISTICS

(Unless otherwise specified, T_A=25°C, V_{CC}=12V for 3.3V, 5V, adjustable version and V_{CC}=18V for the 12V version. I_{LOAD} = 0.2A)

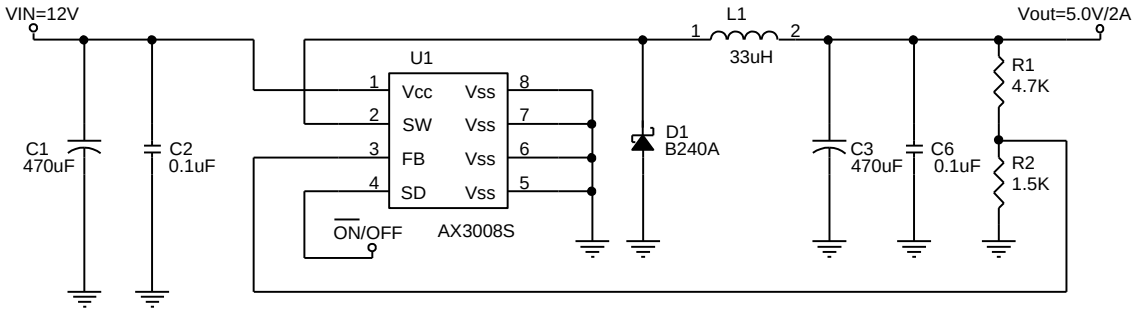
Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Quiescent Current	I_Q	V_{FB}=12V force driver off	-	4	8	mA
Feedback bias current	I_{FB}	V_{FB}=1.3V (Adjustable version only)	-	-10	-50	nA
Shutdown supply Current	I_{SD}	SD pin=5V V_{CC}=30V	-	100	200	uA
Oscillator frequency	F_{OSC}		127	150	173	KHz
Oscillator frequency of short circuit protect	F_{SCP}	(Adjustable) When V_{FB}<0.5V	-	50	-	KHz
		(Fixed)When < V_{OUT}*40%	-	50	-	KHz
Max. Duty Cycle (ON)	DC	V_{FB}=0V force driver on	-	100	-	%
Min. Duty Cycle (OFF)		V_{FB}=12V force driver off	-	0	-	
Current limit	I_{CL}	Pear current, No outside circuit V_{FB}=0V force driver on	2.4	-	-	A
Saturation voltage	V_{SAT}	I_{OUT}=2A, No outside circuit V_{FB}=0V force driver on	-	1.2	1.5	V
SW pin leakage current SW pin=0V	I_{SWL}	No outside circuit V_{FB}=12V force driver off	-	-	-200	uA
SW pin leakage current SW pin=-0.8V		V_{CC}=30V force driver off	-	-5	-	mA
SD pin logic input threshold voltage	V_{IL}	Low (regulator ON)	-	1.3	0.6	V
	V_{IH}	High (regulator OFF)	2.0	1.3	-	V
SD pin logic input current	I_H	V_{SD}=2.5V (OFF)	-	-0.1	-0.5	uA
SD pin input current	I_L	V_{SD}=0.5V (ON)	-	-	-0.01	uA
Thermal shutdown Temp	T_{SD}		-	135	-	°C

❖ ELECTRICAL CHARACTERISTICS (CONTINUED)

Version	Characteristics	Symbol	Conditions	Min	Typ	Max	Units
AX3008-ADJ	Output Feedback voltage	V_{FB}	I_{LOAD} =0.2A V_{OUT} programmed for 3.3V	1.193	1.23	1.267	V
	Efficiency	η	V_{CC} = 12V, I_{LOAD}=2A	-	80	-	%
AX3008-3.3V	Output voltage	V_{OUT}	I_{LOAD}=0.2A	3.20	3.30	3.40	V
	Efficiency	η	V_{CC}= 12V, I_{LOAD}=2A	-	81	-	%
AX3008-5.0V	Output voltage	V_{OUT}	I_{LOAD}=0.2A	4.85	5.00	5.15	V
	Efficiency	η	V_{CC} =12V, I_{LOAD}=2A	-	85	-	%
AX3008-12V	Output voltage	V_{OUT}	I_{LOAD}=0.2A	11.64	12.0	12.36	V
	Efficiency	η	V_{CC}=15V, I_{LOAD} = 2A	-	91	-	%

❖ APPLICATION CIRCUIT

(1) Adjustable Output Voltage Version

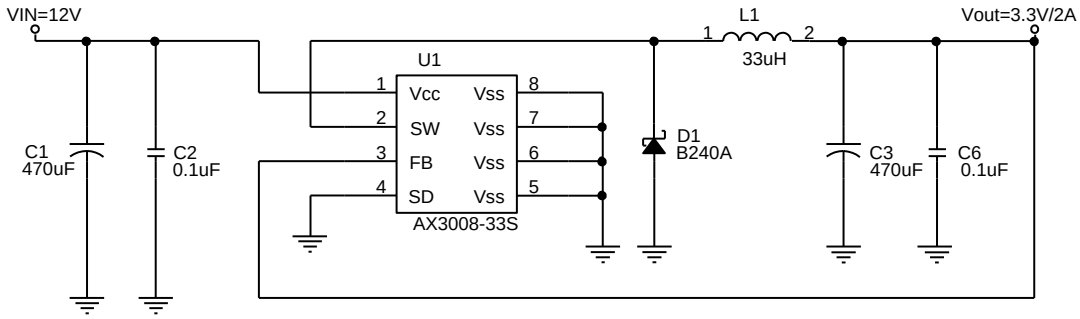


$$V_{OUT} = V_{FB} \times (1 + \frac{R1}{R2}),\ V_{FB} = 1.23V,\ R2 = 0.47K \sim 2.6K$$

Table 1 Resistor select for output voltage setting

V_{OUT}	R2	R1
5V	1.5K	4.7K
	1.8K	5.6K
3.3V	1.5K	2.5K
	1.8K	3.0K
2.5V	1.8K	1.8K
1.8V	1.8K	0.82K
1.5V	1.8K	0.39K

(2) Fixed Output Voltage Version



❖ FUNCTION DESCRIPTION

Pin Functions

V_{CC}

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be presented at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

V_{SS}

Circuit ground.

SW

Internal switch. The voltage at this pin switches between ($+V_{CC}$ – V_{SAT}) and approximately – 0.5V, with a duty cycle of approximately V_{OUT} / V_{CC}. To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be minimized.

Feedback

Senses the regulated output voltage to complete the feedback loop.

SD

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 100uA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of V_{CC}) shuts the regulator down. If this shutdown feature is not needed, the SD pin can be wired to the ground pin.

Thermal Considerations

The all package needs a heat sink under most conditions. The size of the heat sink depends on the input voltage, the output voltage, the load current and the ambient temperature. The junction temperature rises above ambient temperature for a load and different input and output voltages.

The data for these curves was taken with the operating as a buck-switching regulator in an ambient temperature of 25°C (still air). These temperature increments are all approximate and are affected by many factors. Higher ambient temperatures require more heat sinker.

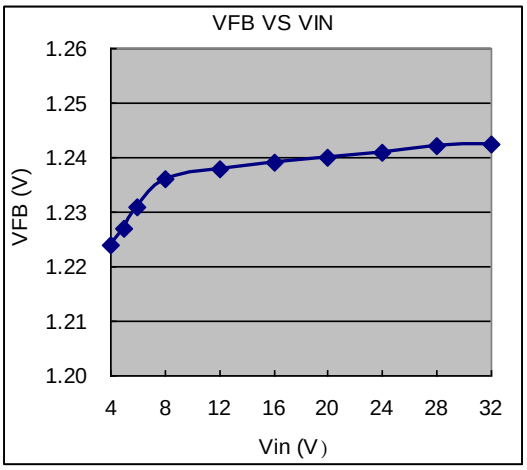
For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper (need connect to the V_{SS} pins) should be used in the board layout, (One exception is the SW(switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature increments are all approximate. The increments are affected by a lot of factors. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are, trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board.

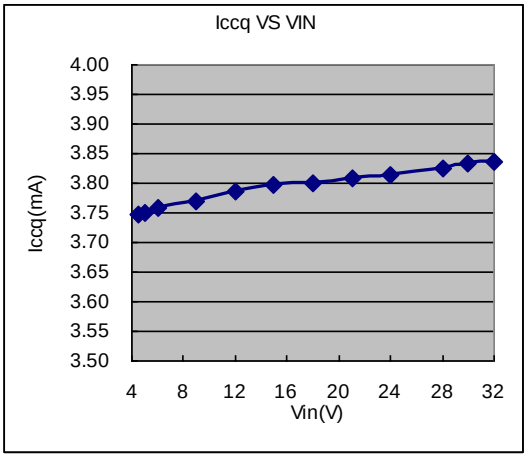
The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.

❖ TYPICAL CHARACTERISTICS

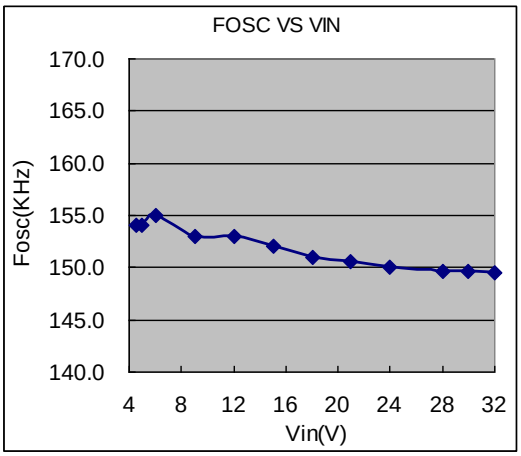
VFB VS VIN



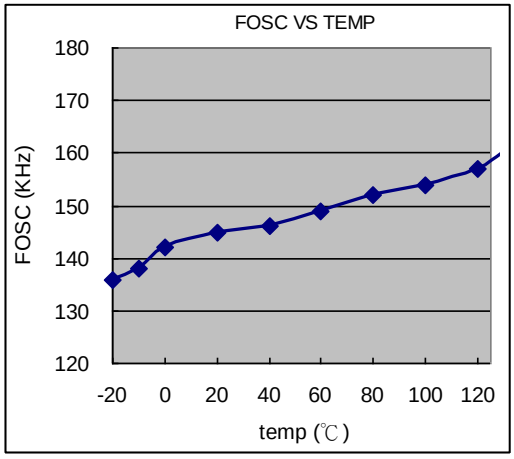
ICCQ VS VIN



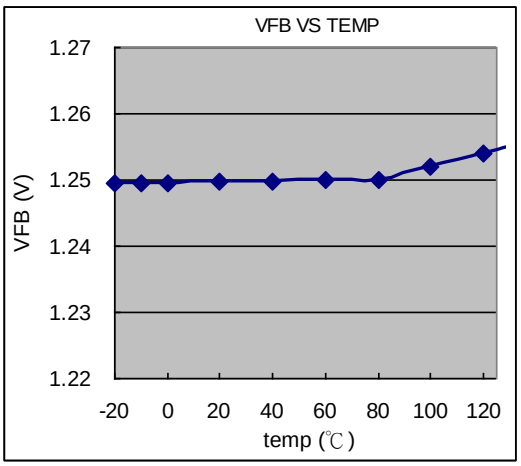
FOSC VS VIN



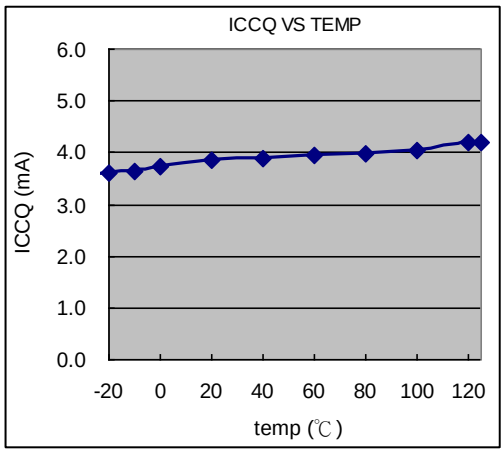
FOSC VS TEMPERATURE



VFB VS TEMPERATURE



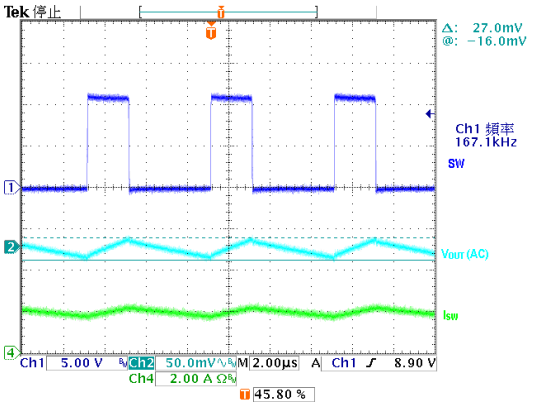
ICCQ VS TEMPERATURE



❖ TYPICAL CHARACTERISTICS (CONTINUOUS)

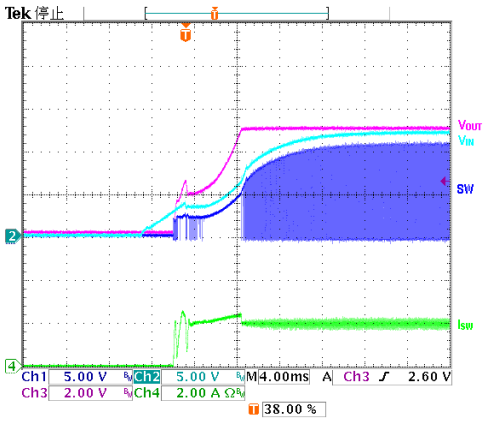
Output Ripple

(V_{IN}=12V, V_{OUT}=5V, I_{OUT}=2A)



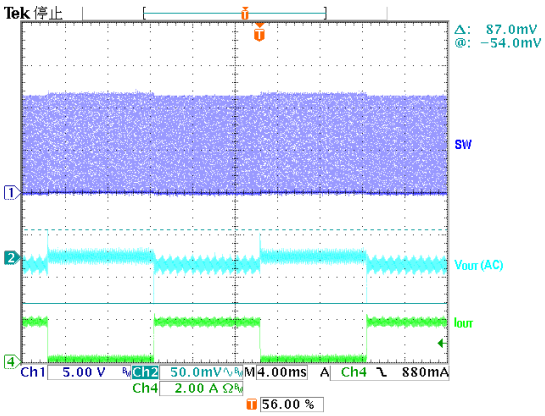
Power on test wave

(V_{IN}=12V, V_{OUT}=5V, I_{OUT}=2A)



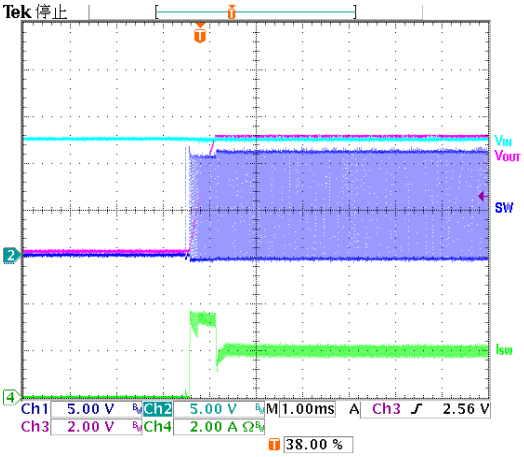
Load Transient Response

(V_{IN}=12V, V_{OUT}=5V, I_{OUT}=0.1~2A)



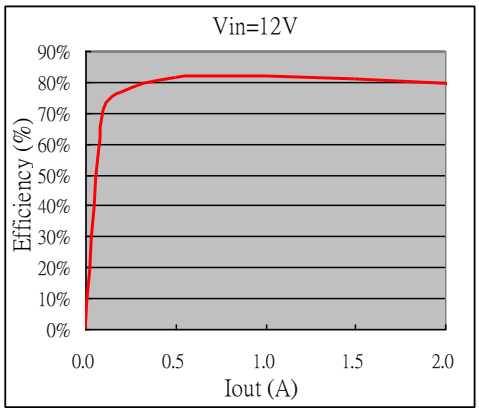
SD on test wave

(V_{IN}=12V, V_{OUT}=5V, I_{OUT}=2A)



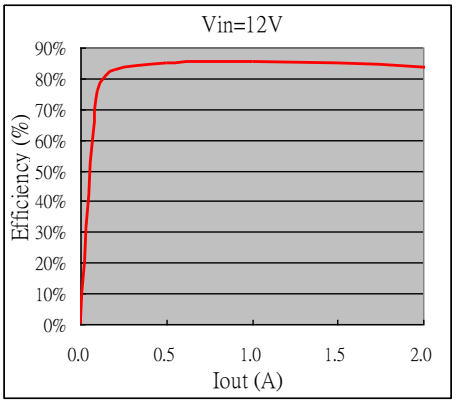
Efficiency

(V_{IN}=12V, V_{OUT}=3.3V)

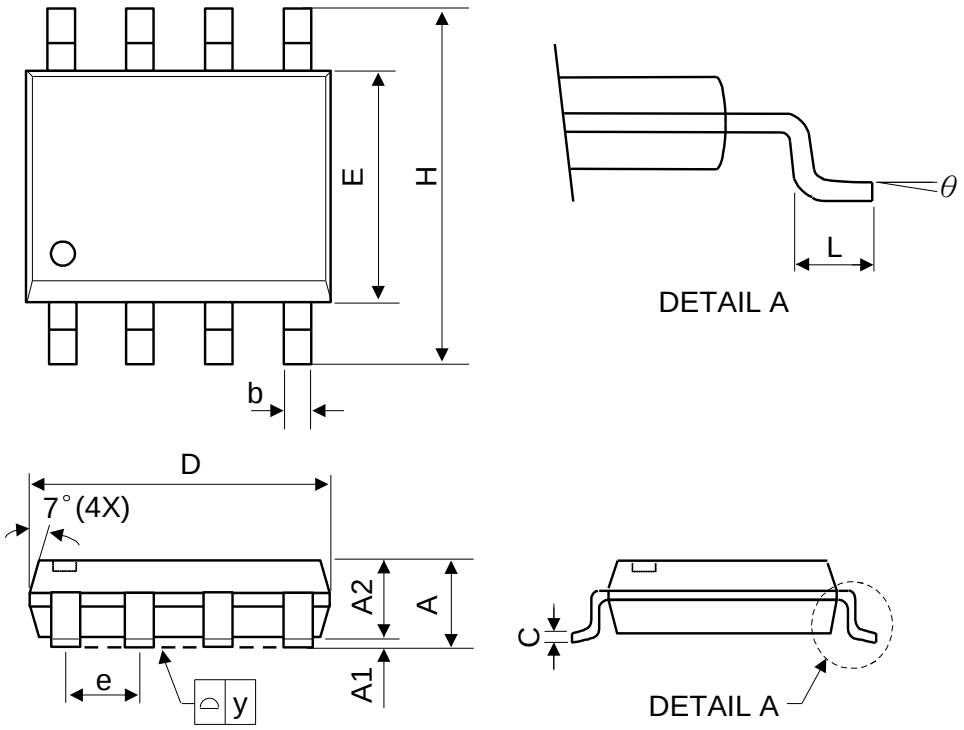


Efficiency

(V_{IN}=12V, V_{OUT}=5.0V)



❖ PACKAGE OUTLINES



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.75	-	-	0.069
A1	0.1	-	0.25	0.04	-	0.1
A2	1.25	-	-	0.049	-	-
C	0.1	0.2	0.25	0.0075	0.008	0.01
D	4.7	4.9	5.1	0.185	0.193	0.2
E	3.7	3.9	4.1	0.146	0.154	0.161
H	5.8	6	6.2	0.228	0.236	0.244
L	0.4	-	1.27	0.015	-	0.05
b	0.31	0.41	0.51	0.012	0.016	0.02
e	1.27 BSC			0.050 BSC		
y	-	-	0.1	-	-	0.004
θ	0°	-	8°	0°	-	8°

Mold flash shall not exceed 0.25mm per side

JEDEC outline: MS-012 AA